REVISIONS (Δ DENOTES CHANGE)				
REV.	**DATE** (YYYY/MM/DD)	**RCN NO**	**DESCRIPTION OF CHANGE**	**UPDATED BY**
-	1987/02/14	RLSD	INITIAL RELEASE	D. MILLER
A	1988/08/25	1481	Revised per customer (vendor) recommendations	D. MILLER
B	1990/12/17	2054	Add Class S(K) criteria, editorial, reference to MIL-H-38534	D. MILLER
C	1991/03/15	2203	Add current density to procurement document	D. MILLER
D	1992/12/08	3183	Update to MIL-H-38534 Rev B	D. MILLER
E	1996/07/10	5227	MIL-H-38534 updated to MIL-PRF-38534	D. MILLER
F	1998/04/16	6716	Clarification, tie in MS XXIII	J. VANDEUSEN
G	2001/12/27	9581	Tie in radiation sample purchase (ie. for LMCPC Class K hybrids)	J. VANDEUSEN
H	2003/03/19	10824	Added 38535 Class changes IAW 38534 Rev E general updates/clarifications	J. VANDEUSEN
J	2004/07/11	11715	Update/clarification IAW ISO 9000-2000, AS9100	J. VANDEUSEN
K	2006/03/01	13372	Update to clarify Rad test requirements	J. VANDEUSEN
L	2010/01/11	16865	Add 4.1.3 flow down to subtier	J. VANDEUSEN
M	2014/01/03	20757	Add 4.1.10 Requirements for record retention	J. VANDEUSEN
N	2015/02/20	176066	Tie in Anaren Doc. #81000, general clarification, remove redundant information now located in 81000.	J. VANDEUSEN
P	2016/02/19	183404	Add gel pak option, remove test sample delivery for Condition E	J. VANDEUSEN
R	2017/07/27	197543	Add "Space Data Package" to "Test data"	J. VANDEUSEN
T	2017/12/11	205458	Add waffle pack specifications	J. VANDEUSEN
U	2018/08/17	209822	Add packaging requirements and update document	J. VANDEUSEN
V	2018/10/02	210539	Add "NO STACK" requirement to packaging	J. VANDEUSEN
W	2021/01/21	309973	Update procurement specification formats, remove MIL-STD-981, Clarify EE data IAW MIL-PRF-38534 Rev L release.	J. VANDEUSEN
Y	2021/12/02	311638	Add Cond F and G, split Cond D and E, update format and delivery format, add assembly for element evaluation, remove 4.1.1, clarify packaging, add wire material/ diameter delivery	J. VANDEUSEN
AA	2022/03/08	312002	Significant changes to better define requirements of our suppliers	J. VANDEUSEN
AB	2022/08/22	312830	Add component orientation requirement to packaging section of document	J. VANDEUSEN
AC	2022/11/09	313219	Add a note for suppliers to separate different semiconductor wafers onto different reels, waffle packs or gel packs per requirements	J. VANDEUSEN

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DRAWN BY	DATE (YYYY/MM/DD)
D. MILLER	1987/02/14

DESIGNER N/A

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APPROVAL SIGNATURES ON FILE

THIRD ANGLE PROJECTION

TTM Technologies

PROCUREMENT SPECIFICATION FOR MICROCIRCUIT/SEMICONDUCTOR

SIZE	CAGE CODE	DOC NO.	
A	31597	1019-1618	
SCALE	**DOC CODE**	**REV**	**SHEET**
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1.0 PURPOSE:

The purpose of this document is to define the supplier requirements of all procured microcircuit elements (Integrated Circuits) and semiconductor elements (diodes, transistor, etc.) used in devices. This document is used in conjunction with Document #81000.

2.0 APPLICATION:

This procedure shall apply to all microcircuit elements and semiconductors as follows:

2.1 **Condition A** - Elements to be used in compliance with MIL-PRF-38534 Class H devices. Element evaluation shall be performed IAW MIL-PRF-38534 Class H and data provided with delivery.

2.2 **Condition B** - Elements intended to be used in full compliance with MIL-PRF-38534 Class H but element evaluation will be the responsibility of the user. Supplier/Mfg is responsible for 100% visual and electrical at the die level. Die level data is not required with delivery.

2.3 **Condition C** - Elements to be used on devices which do not impose MIL-PRF-38534 element evaluation.

2.4 **Condition D** - Elements to be used in compliance with MIL-PRF-38534 Class K devices. Element evaluation shall be performed IAW MIL-PRF-38534 Class K and data provided with delivery.

2.5 **Condition E** - Elements tested IAW the element SCD and data provided with delivery.

2.6 **Condition F** - Elements tested IAW the element SCD with no data required.

2.7 **Condition G** - Elements that are MIL-PRF-38535 (5962) or MIL-PRF-19500 JANKC/JANHC specification qualified.

3.0 DEFINITIONS:

3.1 **Element** - A constituent of the device that contributes directly to its operation (i.e. transistor, diode, integrated circuit, FET).

3.2 **Microcircuit Element** - An active circuit having a high equivalent circuit element density, which is considered as a single part composed of interconnected elements on one or more substrates to perform an electronic circuit function. The microcircuit shall be coated with a transparent glass or other approved coating to a minimum thickness of 600nm for SiO_2 and 200nm for Si_3N_4 and shall cover all conductors except bonding pads (as applicable by design).

Internal thin film conductors on a substrate (metallization stripes, contact areas, bonding interfaces, etc.) shall be designed so that no properly fabricated conductor shall experience in normal operation (at worst case specified operating conditions), a current density in excess of the maximum allowable value shown below for the applicable conductor material:

Conductor Material	Maximum Allowable Current Density
Aluminum (99.99 percent pure or doped) without glassivation.	2×10^5 A/cm^2
Aluminum (99.99 percent pure or doped) glassivated.	5×10^5 A/cm^2
Gold	6×10^5 A/cm^2
All other (unless otherwise specified)	2×10^5 A/cm^2

The current density shall be calculated at the point of maximum current density (ie. greatest current per unit cross section) for the specified device type and schematic or configuration.

3.3 **Semiconductor Element** - Active semiconductor elements other than microcircuites (e.g. transistors, diodes, FET, or silicon controlled rectifiers (SCRs).

3.4 **Wafer Lot** - Wafer lots consist of microcircuit and semiconductor wafers formed into lots at the start of wafer fabrication for homogeneous processing as a group. Each lot is assigned a unique identifier or code to provide traceability and maintain lot integrity throughout the fabrication process. Wafer lot processing as a homogeneous group is accomplished by any of the following procedures, providing process schedules and controls are sufficiently maintained, to assure identical processing in accordance with process instructions of all wafers in the lot:

a. Batch processing of all wafers in the wafer lot through the same machine process steps simultaneously.

b. Continuous or sequential processing (wafer by wafer or batch portions of wafer lot) of all wafers through the same machine or process steps.

c. Parallel processing of portions of the wafer lot through multiple machines or process stations on the same certified line, provided statistical quality control (SQC) assures and demonstrates correlation between stations and separately processed portions of the wafer lot.

3.5 **Production Lot** - A production lot consists of an element type manufactured from the same basic raw materials on the same production line, processed under the same manufacturing techniques and controls using the same type of equipment. Each lot shall be assigned a unique identification that provides traceability to all processing steps.

3.6 **Inspection Lot** - An inspection lot shall consist of microcircuits/semiconductors of a single circuit type submitted at one time for inspection to determine compliance with the applicable requirements and acceptable criteria.

3.7 **Element Evaluation** - As applicable to this specification may consist of Microcircuit/Semiconductor die evaluated IAW MIL-PRF-38534 (Class H or K) or as specified in the element SCD.

3.8 **Environmentally Controlled Area** - An area which exhibits the following conditions:

3.8.1 Temperature shall be 25°C (+3/-5°C)

3.8.2 Class 8 per ISO 14644-1, -2 or Class 100,000 per MIL-STD-209

3.8.3 Humidity - RH 30 to 65%

3.8.4 Positive Pressure .01" water column or greater

3.8.5 Element Storage shall be in a nitrogen atmosphere dry box.

4.0 GENERAL INFORMATION:

4.1 General:

4.1.1 All electrical test (100%) and visual inspection (100%) may be performed at the wafer level provided all rejects are identified and removed from the lot.

4.1.2 When assembly is required for element evaluation, the build process may use similar assembly methods, materials and conditions used in typical device production. The processes may include:

- Die attach material shall be selected based on the element type (power elements may be mounted with solder, eutectic or thermally conductive epoxy and low power elements may be mounted with conductive or nonconductive epoxy)
- Wire bond material and size shall be selected based on the element type (power elements may be wired with large diameter aluminum wire 5, 8, 10, 12, 15 or 20mil wire and low power elements may be wired with 0.7, 1.0, 1.25, 1.3 or 2.0 mil gold wire).

4.1.3 **Other Documentation** - Evidence of the suppliers inspection, assembly, screening and testing shall be maintained at the suppliers facility. The evidence maintained should include the following:

a. Name of operation, specification number and revision of each process or test.

b. Part number, wafer number and associated manufacturer internal lot identification number(s).

c. Date(s) of test and operator identification.

d. Calibration control number and calibration due date of all test equipment.

e. Quantity tested and rejected for each process or test and actual quantity tested if sampled.

f. For electrical test, test program number and revision.

4.2 Packaging/Marking Best Practices:

4.2.1 **Packaging**:

Packaging requirements are placed on the purchase order. This requirement may be waffle pack, gel pack, or tape and reel.

Components must all be oriented in the same direction in the package and this orientation must be maintained for each shipment.

If no waffle pack is defined, then the supplier may use a waffle pack that does not allow either greater than 45 degrees of part rotation in the cavity, and the cavity depth will be such that the part cannot either flip or stand on end during transit.

If no gel pack is defined, then the supplier may use a gel pack that provides the same placement/orientation of the parts on the gel for each pack and for each shipment of that part.

Each individual reel, waffle pack or gel pack shall not contain either mixed wafers or mixed lots of components.

Tape and reel requirements are defined in specification 302-032-00.

Refer to element packaging table (see next page).

NOTE*: *For any shipment all components are to be oriented in the same direction in the specific packaging type. This orientation is to be maintained for each succeeding shipment.

4.2.2 **Package/Container Marking**:

The element part number, manufacturer's name, manufacturer's lot/wafer number and quantity shall appear on the paperwork and on each package/container/waffle tray/gel pack. Package/container marking shall be sufficient for inspection lot traceability.

Element Type		Packaging Requirement		
Semiconductor elements (transistor and diode dice)		2" x 2" black conductive waffle tray with: - Carrier well must be deep enough so that the die surface is below the top plane of the waffle tray. - Protective sheet or pad as applicable. Optimum insert is Entegris H20-001-0715 - Secure lid with single clip. Dual clips not allowed. - Hinged lids are not allowed unless prior approval is obtained. - No stacking of waffle packs.	OR	2" x 2" black conductive gel pack with vacuum release for auto pick and place capability: - Secure lid with single clip. Dual clips not allowed. - Hinged lids are not allowed unless prior approval is obtained. - No stacking of waffle packs.
Microcircuit elements (integrated circuit dice)	Without air bridges	2" x 2" black conductive waffle tray with: - Carrier well must be deep enough so that the die surface is below the top plane of the waffle tray - Protective sheet or pad as applicable. Optimum insert is Entegris H20-001-0715 - Secure lid with single clip. Dual clip not allowed - Hinged lids are not allowed unless prior approval is obtained. - No stacking of waffle packs.	OR	2" x 2" black conductive gel pack with vacuum release for auto pick and place capability: - Secure lid with single clip. Dual clips not allowed - Hinged lids are not allowed unless prior approval is obtained. - No stacking of waffle packs.
	With air bridges	ONLY		2" x 2" black conductive gel pack with vacuum release for auto pick and place capability: - secure lid with single clip. Dual clips not allowed. - Hinged lids are not allowed unless prior approval is obtained from TTM - No stacking of waffle packs.

Element Packaging Requirements Table 1

Element Type	Packaging Requirement
For elements which will not fit into a 2" x 2" waffle tray or gel pack	Elements shall be packaged in a manner that: 1. Physically restrained from vibration and mechanically isolated from shock that could cause physical damage or electrical degradation of the elements. 2. Sealed in an electrostatic bag.
For elements that are placed in tape and reel	Tape and reel requirements are defined in document 303-032.00, Specification for Components to be delivered in Tape and Reel Packaging. **EACH INDIVIDUAL REEL SHALL NOT CONTAIN EITHER MIXED WAFERS OR MIXED LOTS OF COMPONENTS.**

Element Packaging Requirements Table 1 (Continued)

5.0 PROCEDURE:

5.1 Condition A - Supplier requirements for semiconductor elements (transistor and diode dice).

5.1.1 As required by MIL-PRF-38534 Class H, the supplier shall perform 100% electrical testing at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications/element drawing. Data recording and pass/fail submittal quantity is not required.

5.1.2 The supplier shall have an accepted internal document for visual inspection to MIL-STD-750, Method 2069, 2070, 2072, 2073 as applicable.

5.1.3 As required by MIL-PRF-38534 Class H, the supplier shall perform 100% visual inspection to an in-house control document in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.1.4 Element evaluation shall be performed by the supplier for each production/inspection lot in accordance with MIL-PRF-38534 for Class H elements.

5.1.5 Delivery Conditions:

5.1.5.1 Packaging/Marking: Packaging and marking shall be IAW Para 4.2.

5.1.5.2 Required Documentation:

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element Evaluation Screening/Attribute Data and as applicable, the wire material and diameter

d. Element Test Data

5.2 Condition A - Supplier requirements for microcircuit elements (integrated circuits).

5.2.1 As required by MIL-PRF-38534 Class H, the supplier shall perform 100% electrical testing at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications/element drawing. Data recording and pass/fail submittal quantity is not required.

5.2.2 The supplier shall have an accepted internal document for visual inspection to MIL-STD-883 Method 2010 Condition B.

5.2.3 As required by MIL-PRF-38534 Class H, the supplier shall perform 100% visual inspection to an in-house approved control document in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.2.4 Element evaluation shall be performed by the supplier on each wafer lot in accordance with MIL-PRF-38534 for Class H elements.

5.2.5 Delivery Conditions:

5.2.5.1 Packaging/Marking: Packaging and marking shall be IAW Para 4.2.

5.2.5.2 Required Documentation:

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element Evaluation Screening/Attribute Data and as applicable, the wire material and diameter

d. Element Test Data

5.3 Condition B - Supplier requirements of all semiconductor elements (transistors and diode dice) and microcircuit (integrated circuits).

5.3.1 As required by MIL-PRF-38534 Class H, each die shall be 100% electrically tested at the die level 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications. Data recording and pass/fail submittal quantity is not required.

5.3.2 As required by MIL-PRF-38534 Class H, the supplier shall have an accepted internal document for Visual Inspection to MIL-STD-883 Method 2010 Condition B or MIL-STD-750 Method 2069, 2070, 2072, 2073 as applicable. The supplier shall perform visual inspection 100% in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.3.3 Delivery Conditions:

5.3.3.1 Packaging/Marking: Packaging and marking shall be IAW Para 4.2.

5.3.3.2 Required Documentation:

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

5.4 Condition C - Supplier requirements of all semiconductor elements (transistors and diode dice) and microcircuit (integrated circuits).

5.4.1 The supplier shall perform 100% electrical testing at 25°C to manufacturers internal requirements. Data recording and pass/fail submittal quantity is not required.

5.4.2 Devices shall be capable of meeting the visual requirements of MIL-STD-750 test method for semiconductor devices Method 2069, 2070, 2072, 2073 and MIL-STD-883 Method 2010 Condition B for microcircuits. Visual pass/fail submittal quantity is not required.

5.4.3 Delivery Conditions:

5.4.3.1 Packaging/Marking: Packaging and marking shall be IAW Para 4.2.

5.4.3.2 Required Documentation:

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

5.5 Condition D - Supplier requirements for semiconductor elements (transistor and diode dice) and for radiation (as applicable) tested elements.

5.5.1 As required by MIL-PRF-38534 Class K, the supplier shall perform 100% electrical testing at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications/element drawing. Data recording and pass/fail submittal quantity is not required.

5.5.2 The supplier shall have an accepted internal document for visual inspection to MIL-STD-750, Method 2069, 2070, 2072, 2073 as applicable.

5.5.3 As required by MIL-PRF-38534 Class K, the supplier shall perform 100% visual inspection to an in-house control document in an environmentally controlled areas and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.5.4 Element evaluation shall be performed by the supplier for each wafer lot in accordance with MIL-PRF-38534 for Class K elements. Test samples shall be delivered with each lot.

5.5.5 When specified on the purchase order, 12 die from the same lot shall be packaged and tested with recorded data. The packaged die shall be shipped prior to completion of Class K element evaluation. The 12 packaged die are above and beyond the Class K element evaluation and will be used for radiation testing.

5.5.6 **Delivery Conditions:**

5.5.6.1 **Packaging/Marking:** Packaging and marking shall be IAW Para 4.2.

5.5.6.2 Test samples shall be delivered with each lot.

5.5.6.3 **Required Documentation:**

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element Evaluation Screening/Attribute Data and as applicable, the wire material and diameter

d. Element Test Data

5.6 **Condition D -** Supplier requirements for microcircuit elements (Integrated Circuits) and for radiation (as applicable) tested elements.

5.6.1 As required by MIL-PRF-38534 Class K, the supplier shall perform 100% electrical testing at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Elements shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications/element drawing. Data recording and pass/fail submittal quantity is not required.

5.6.2 The supplier shall have an accepted internal document for visual inspection to MIL-STD-883 Method 2010 Condition A.

5.6.3 As required by MIL-PRF-38534 Class K, the supplier shall perform 100% visual inspection to an in-house approved control document in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.6.4 Element evaluation shall be performed by the supplier for each wafer lot in accordance with MIL-PRF-38534 for Class K elements. Test samples shall be delivered with each lot.

5.6.5 When specified on the purchase order, 12 die from the same lot shall be packaged and tested with recorded data. The packaged die shall be shipped prior to completion of Class K element evaluation. The 12 packaged die are above and beyond the Class K element evaluation and will be used for radiation testing.

5.6.6 **Delivery Conditions:**

5.6.6.1 **Packaging/Marking:** Packaging and marking shall be IAW Para 4.2.

5.6.6.2 Test samples shall be delivered with each lot.

5.6.6.3 **Required Documentation:**

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element Evaluation Screening/Attribute Data and as applicable, the wire material and diameter

d. Element Test Data

5.7 **Condition E -** The Supplier shall test to the requirements called out in the SCD for the semiconductor elements (transistors and diode dice) and microcircuits (integrated circuits).

5.7.1 As required by MIL-PRF-38534 Class H or K, each die shall be 100% electrically tested at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications. Data recording and pass/fail submittal quantity is not required.

5.7.2 As required by MIL-PRF-38534 Class H or K, the supplier shall have an accepted internal document for Visual Inspection to the applicable MIL-PRF specification or to MIL-STD-883 Method 2010 Condition A or B, MIL-STD-750 Method 2069, 2070, 2072, 2073 as applicable. The supplier shall perform visual inspection 100% in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.7.3 **Delivery Conditions**:

5.7.3.1 **Packaging/Marking:** Packaging and marking shall be IAW Para 4.2.

5.7.3.2 **Required Documentation:**

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element Evaluation Screening/Attribute Data and as applicable, the wire material and diameter

d. Element Test Data

5.8 **Condition F -** The Supplier shall test to the requirements called out in the SCD for the semiconductor elements (transistors and diode dice) and microcircuits (integrated circuits).

5.8.1 As required by MIL-PRF-38534 Class H or K, each die shall be 100% electrically tested at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications. Data recording and pass/fail submittal quantity is not required.

5.8.2 As required by MIL-PRF-38534 Class H or K, the supplier shall have an accepted internal document for Visual Inspection to the applicable MIL-PRF specification or to MIL-STD-883 Method 2010 Condition A or B, MIL-STD-750 Method 2069, 2070, 2072, 2073 as applicable. The supplier shall perform visual inspection 100% in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.8.3 **Delivery Conditions**:

5.8.3.1 **Packaging/Marking:** Packaging and marking shall be IAW Para 4.2.

5.8.3.2 **Required Documentation:**

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. Element traceability to the SCD

d. Data available upon request

5.9 **Condition G -** Element is MIL-PRF-38535, 5962 qualified (microcircuit element) or JANKC/JANHC (semiconductor element) qualified. Element evaluation is not required by the vendor.

5.9.1 As required by MIL-PRF-38534 or applicable qualified line, each die shall be 100% electrically tested at the die level at 25°C to ensure compliance to the manufacturer's internal requirements. Devices shall be capable of operating over full temperature range to minimum and maximum electrical data book specifications. Data recording and pass/fail submittal quantity is not required.

5.9.2 The supplier shall have an accepted internal document for Visual Inspection to the applicable MIL-PRF specification or to MIL-STD-883 Method 2010 Condition A or B, MIL-STD-750 Method 2069, 2070, 2072, 2073 as applicable. The supplier shall perform visual inspection 100% in an environmentally controlled area and ensure compliance to all visual and mechanical specifications. Visual pass/fail submittal quantity is not required.

5.9.3 **Delivery Conditions**:

5.9.3.1 **Packaging/Marking:** Packaging and marking shall be IAW Para 4.2.

5.9.3.2 **Required Documentation:**

a. Certificate of Compliance, as defined in Document #81000.

b. OEM C of C and Distributor C of C (if supplied by distributor)

c. MIL-PRF element traceability

d. Data available upon request

6.0 ACCEPT/REJECT CRITERIA:

6.1 Accept all lots which pass the applicable paragraphs of this procedure and the element drawing.

6.2 Reject any device(s) and separate it from the lot which fails an electrical parameter or visual/mechanical criteria.

6.3 Reject any wafer lot which does not pass element evaluation or radiation testing.